

STATUS OF THE CLAIMS

The status of the claims of the present application stands as follows:

1. **(Original)** An integrated circuit having a plurality of circuits that include at least one I/O circuit and at least one logic circuit, comprising:
 - a) a contact layer having a plurality of contacts for electrically connecting the integrated circuit to packaging;
 - b) a power grid comprising a plurality of metal layers for providing power to the at least one I/O circuit and the at least one logic circuit;
 - c) a semiconductor device layer in electrical communication with said power grid; and
 - d) a wiring layer interposed between said contact layer and said power grid and electrically connecting said plurality of contacts with said power grid, said wiring layer including a plurality of wires each having a length extending partly along a first direction and partly along a second direction different from said first direction.
2. **(Original)** An integrated circuit according to claim 1, wherein each of at least some of said plurality of wires have a ring-shaped configuration.
3. **(Original)** An integrated circuit according to claim 2, wherein said ring-shaped configuration is rectangular.
4. **(Currently Amended)** An integrated circuit according to claim 2, wherein ~~at least some of said ones of said~~ plurality of wires having said ring-shaped configuration are arranged concentrically with one another.
5. **(Currently Amended)** An integrated circuit according to claim 1, wherein said plurality of contacts includes a plurality of first contacts and a plurality of second contacts located alternately with respect to said plurality of first contacts along a plurality of lines, said ~~wiring layer~~ plurality of wires including a plurality of first wires and a plurality of second wires wherein each of said plurality of second wires is laterally spaced from a corresponding one of said plurality of first wires, and each of said plurality of first wires is located on one side of a corresponding one of said plurality of lines and a corresponding one of said plurality

of second wires is located on the opposite side of said corresponding one of said plurality of lines.

6. **(Currently Amended)** An integrated circuit according to claim 1, wherein said plurality of wires ~~are~~ is arranged in concentric rings.
7. **(Original)** An integrated circuit according to claim 1, wherein said plurality of wires includes a plurality of Vdd wires and a plurality of ground wires.
8. **(Original)** An integrated circuit according to claim 7, further comprising a plurality of Vddx wires.
9. **(Original)** An integrated circuit according to claim 1, wherein said plurality of contacts are arranged in a square pattern having diagonal symmetry and major axis symmetry, said plurality of wires arranged in concentric square rings.
10. **(Original)** An integrated circuit having a plurality of circuits that include at least one I/O circuit and at least one logic circuit, comprising:
 - a) a contact layer having a plurality of contacts for electrically connecting the integrated circuit to packaging;
 - b) a power grid comprising a plurality of metal layers for providing power to the at least one I/O circuit and the at least one logic circuit;
 - c) a semiconductor device layer in electrical communication with said power grid; and
 - d) a wiring layer interposed between, and electrically connecting together, said contact layer and said power grid, said wiring layer including a plurality of wires having ring-shaped configurations.
11. **(Original)** An integrated circuit according to claim 10, wherein said ring-shaped configurations are rectangular.
12. **(Currently Amended)** An integrated circuit according to claim 10, wherein ~~at least some of said ones of~~ said plurality of wires having said ring-shaped configurations are arranged concentrically with one another.

13. **(Currently Amended)** An integrated circuit according to claim 10, wherein said plurality of contacts includes a plurality of first contacts and a plurality of second contacts located alternatingly with respect to said plurality of first contacts along a plurality of lines, said ~~wiring layer~~ plurality of wires including a plurality of first wires and a plurality of second wires wherein each of said plurality of second wires is laterally spaced from a corresponding one of said plurality of first wires, and each of said plurality of first wires is located on one side of a corresponding one of said plurality of lines and a corresponding one of said plurality of second wires is located on the opposite side of said corresponding one of said plurality of lines.
14. **(Original)** An integrated circuit according to claim 10, wherein said plurality of wires includes a plurality of Vdd wires and a plurality of ground wires.
15. **(Currently Amended)** An integrated circuit according to claim ~~15~~14, further comprising a plurality of Vddx wires.
16. **(Currently Amended)** An integrated circuit according to claim 10, wherein said plurality of contacts ~~are~~ is arranged in a square pattern having diagonal symmetry and major axis symmetry, said plurality of wires arranged in concentric square rings.
17. **(Original)** An integrated circuit according to claim 10, wherein said power grid comprises a plurality of layers each comprising wires having longitudinal axes all extending in the same direction.
18. **(Original)** A device, comprising:
- a) a power supply; and
 - b) an integrated circuit having at least one I/O circuit and at least one logic circuit, said integrated circuit comprising:
 - i) a contact layer having a plurality of contacts in electrical communication with said power supply;
 - ii) a power grid comprising a plurality of metal layers for providing power to said at least one I/O circuit and said at least one logic circuit;
 - iii) a semiconductor device layer in electrical communication with said power grid; and

iv) a wiring layer interposed between said contact layer and said power grid and electrically connecting at least some of said contacts with said power grid, said wiring layer including a plurality of wires each having a length extending partly along a first direction and partly along a second direction different from said first direction.

19. **(Original)** A device according to claim 18, wherein each of at least some of said plurality of wires have a ring-shaped configuration.
20. **(Original)** A device according to claim 18, wherein said plurality of wires are configured and arranged in concentric rings.